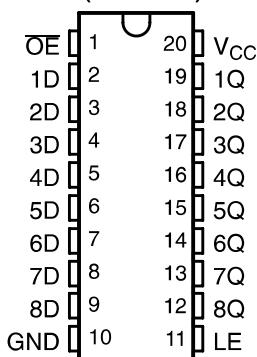


SN54BCT573, SN74BCT573 OCTAL TRANSPARENT D-TYPE LATCHES WITH 3-STATE OUTPUTS

SCBS071B – AUGUST 1990 – REVISED MARCH 2003

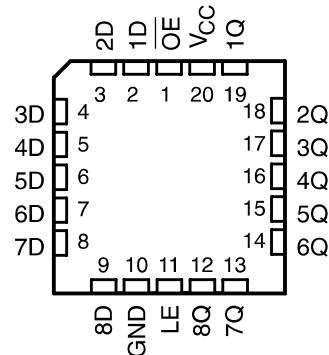
- Operating Voltage Range of 4.5 V to 5.5 V
- State-of-the-Art BiCMOS Design
- Significantly Reduces I_{CCZ}
- Full Parallel Access for Loading

SN54BCT573 . . . J OR W PACKAGE
SN74BCT573 . . . DW, N, OR NS PACKAGE
(TOP VIEW)



- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

SN54BCT573 . . . FK PACKAGE
(TOP VIEW)



description/ordering information

These 8-bit latches feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

The eight latches of the 'BCT573 devices are transparent D-type latches. While the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When the latch enable is taken low, the Q outputs are latched at the logic levels that were set up at the D inputs.

A buffered output-enable (\overline{OE}) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without interface or pullup components.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

\overline{OE} does not affect internal operations of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

ORDERING INFORMATION

T _A	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	PDIP – N	Tube	SN74BCT573N	SN74BCT573N
	SOIC – DW	Tube	SN74BCT573DW	BCT573
	SOP – NS	Tape and reel	SN74BCT573DWR	
-55°C to 125°C	CDIP – J	Tube	SN74BCT573NSR	BCT573
	CFP – W	Tube	SNJ54BCT573J	SNJ54BCT573J
	LCCC – FK	Tube	SNJ54BCT573W	SNJ54BCT573W
			SNJ54BCT573FK	SNJ54BCT573FK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



POST OFFICE BOX 655303 • DALLAS, TEXAS 75265
POST OFFICE BOX 1443 • HOUSTON, TEXAS 77251-1443

Copyright © 2003, Texas Instruments Incorporated
On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

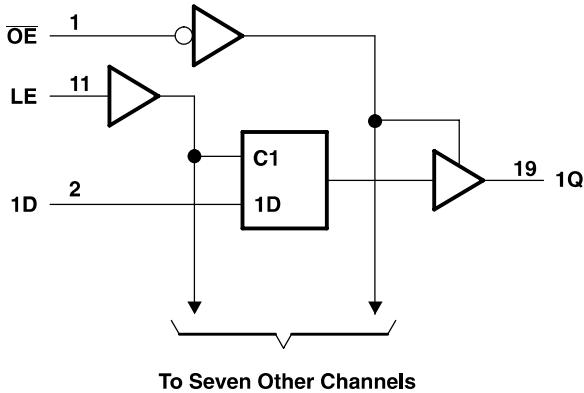
SN54BCT573, SN74BCT573
OCTAL TRANSPARENT D-TYPE LATCHES
WITH 3-STATE OUTPUTS

SCBS071B – AUGUST 1990 – REVISED MARCH 2003

FUNCTION TABLE
(each latch)

INPUTS			OUTPUT
OE	LE	D	Q
L	H	H	H
L	H	L	L
L	L	X	Q ₀
H	X	X	Z

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC}	-0.5 V to 7 V
Input voltage range, V _I (see Note 1)	-0.5 V to 7 V
Voltage range applied to any output in the disabled or power-off state, V _O	-0.5 V to 5.5 V
Voltage range applied to any output in the high state, V _O	-0.5 V to V _{CC}
Input clamp current, I _{IK} (V _I < 0)	-30 mA
Current into any output in the low state:	
SN54BCT573	96 mA
SN74BCT573	128 mA
Package thermal impedance, θ _{JA} (see Note 2): DW package	58°C/W
N package	69°C/W
NS package	60°C/W
Storage temperature range, T _{stg}	-65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51-7.

SN54BCT573, SN74BCT573
OCTAL TRANSPARENT D-TYPE LATCHES
WITH 3-STATE OUTPUTS

SCBS071B – AUGUST 1990 – REVISED MARCH 2003

recommended operating conditions (see Note 3)

		SN54BCT573			SN74BCT573			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC}	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V _{IH}	High-level input voltage	2			2			V
V _{IL}	Low-level input voltage			0.8			0.8	V
I _{IK}	Input clamp current			-18			-18	mA
I _{OH}	High-level output current			-12			-15	mA
I _{OL}	Low-level output current			48			64	mA
T _A	Operating free-air temperature	-55		125	0		70	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	SN54BCT573			SN74BCT573			UNIT
		MIN	TYP†	MAX	MIN	TYP†	MAX	
V _{IK}	V _{CC} = 4.5 V, I _I = -18 mA			-1.2			-1.2	V
V _{OH}	V _{CC} = 4.5 V	I _{OH} = -3 mA	2.4	3.3	2.4	3.3		V
		I _{OH} = -12 mA	2	3.2				
		I _{OH} = -15 mA			2	3.1		
V _{OL}	V _{CC} = 4.5 V	I _{OL} = 48 mA	0.38	0.55				V
		I _{OL} = 64 mA			0.42	0.55		
I _I	V _{CC} = 5.5 V, V _I = 5.5 V			0.4			0.4	mA
I _{IH}	V _{CC} = 5.5 V, V _I = 2.7 V			20			20	µA
I _{IL}	V _{CC} = 5.5 V, V _I = 0.5 V			-0.6			-0.6	mA
I _{OS‡}	V _{CC} = 5.5 V, V _O = 0	-100		-225	-100		-225	mA
I _{OZH}	V _{CC} = 5.5 V, V _O = 2.7 V			50			50	µA
I _{OZL}	V _{CC} = 5.5 V, V _O = 0.5 V			-50			-50	µA
I _{CCL}	V _{CC} = 5.5 V, Outputs open			62			62	mA
I _{CCH}	V _{CC} = 5.5 V, Outputs open			8			8	mA
I _{CCZ}	V _{CC} = 5.5 V, Outputs open			8			8	mA
C _i	V _{CC} = 5 V, V _I = 2.5 V or 0.5 V			5.5			5.5	pF
C _o	V _{CC} = 5 V, V _O = 2.5 V or 0.5 V			7.5			7.5	pF

† All typical values are at V_{CC} = 5 V, T_A = 25°C.

‡ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

		V _{CC} = 5 V, T _A = 25°C		SN54BCT573		SN74BCT573		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t _w	Pulse duration, LE high	4		4		4		ns
t _{su}	Setup time, data before LE↓	1		2.5		1		ns
t _h	Hold time, data after LE↓	4		4		4		ns



POST OFFICE BOX 655303 • DALLAS, TEXAS 75265
 POST OFFICE BOX 1443 • HOUSTON, TEXAS 77251-1443

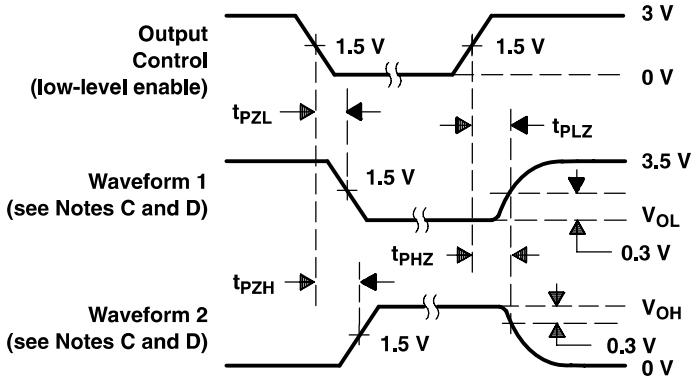
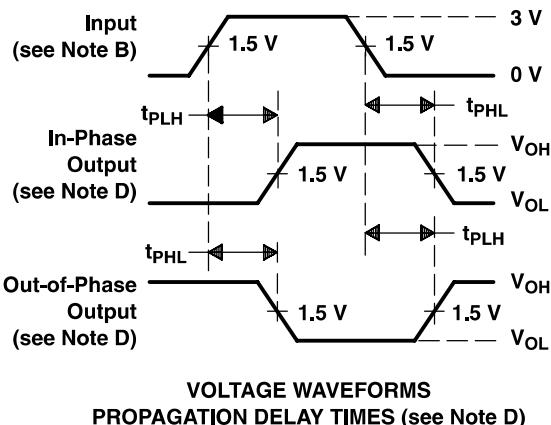
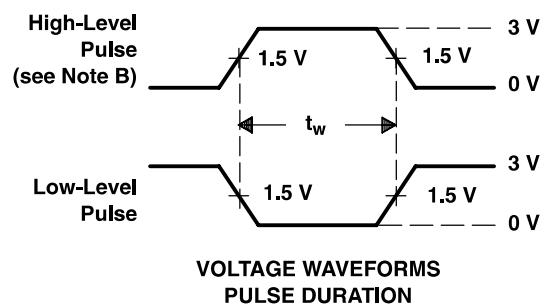
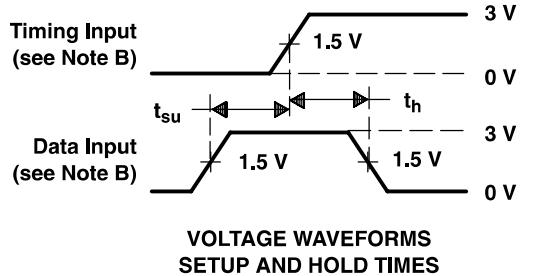
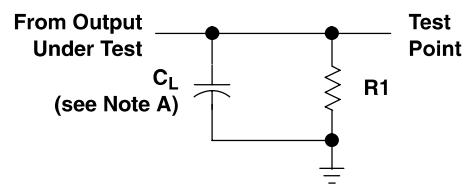
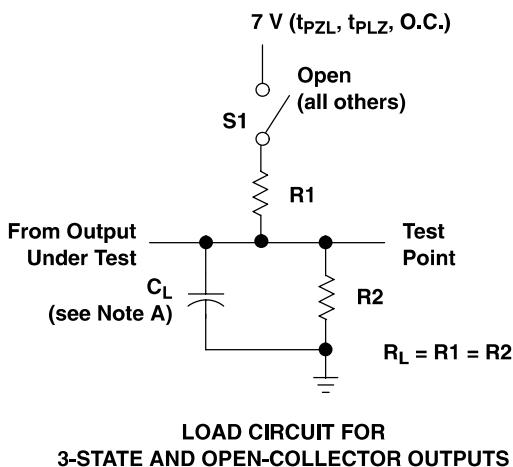
**SN54BCT573, SN74BCT573
OCTAL TRANSPARENT D-TYPE LATCHES
WITH 3-STATE OUTPUTS**

SCBS071B – AUGUST 1990 – REVISED MARCH 2003

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 5 \text{ V},$ $T_A = 25^\circ\text{C}$			SN54BCT573	SN74BCT573	UNIT	
			MIN	TYP	MAX	MIN	MAX		
t_{PLH}	D	Q	2	5	7.2	1	9.8	2	8.4
t_{PHL}			2.8	5.9	8.2	1.5	10.3	2.8	9.6
t_{PLH}	LE	Q	2.4	6.1	7.2	2	9.7	2.4	8.1
t_{PHL}			2.9	5.2	7.1	2	8.8	2.9	7.8
t_{PZH}	\bar{OE}	Q	3	6.2	8.5	2.5	11	3	10.4
t_{PZL}			4.3	7.1	9.3	3.5	11.5	4.3	11
t_{PHZ}	\bar{OE}	Q	2.2	3.9	5.6	1.5	7.2	2.2	6
t_{PLZ}			1.7	3.6	5.2	1	7	1.7	6

PARAMETER MEASUREMENT INFORMATION



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10$ MHz, $t_r = t_f \leq 2.5$ ns, duty cycle = 50%.
 - C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
 - Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. When measuring propagation delay times of 3-state outputs, switch S1 is open.
 - F. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
(1)	(2)	Drawing	(2)	(6)	(3)	(4/5)				
SN74BCT573DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	0 to 70	BCT573 Samples
SN74BCT573DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	0 to 70	BCT573 Samples
SN74BCT573N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	NIPDAU	N / A for Pkg Type	0 to 70	SN74BCT573N Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.**(2) RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.



www.ti.com

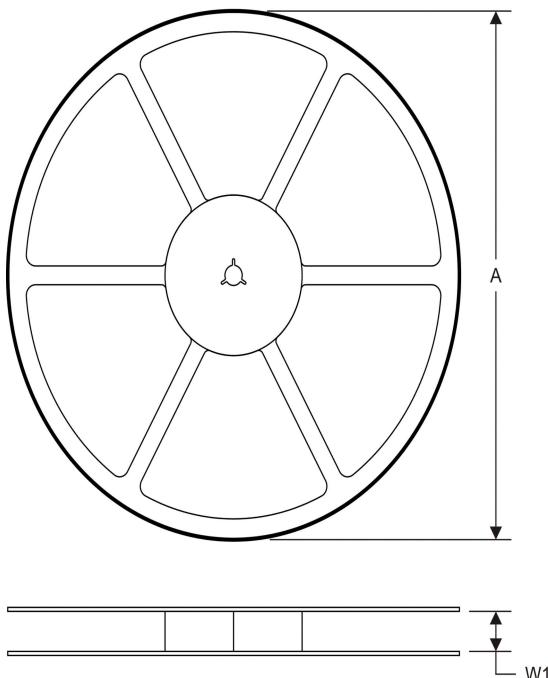
PACKAGE OPTION ADDENDUM

6-Feb-2020

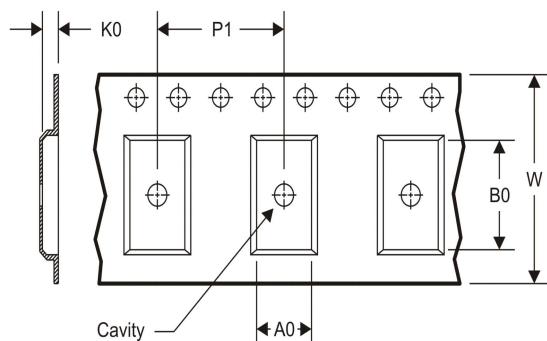
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



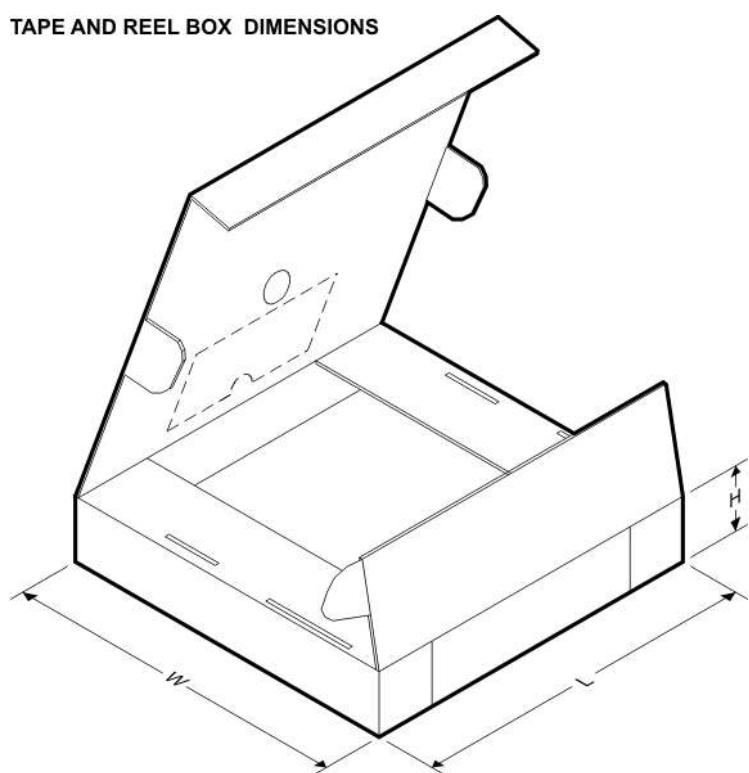
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74BCT573DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS



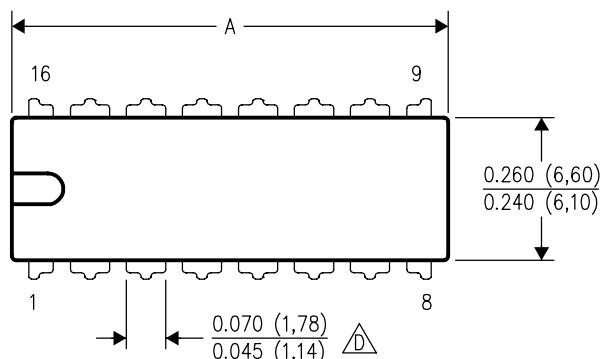
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74BCT573DWR	SOIC	DW	20	2000	367.0	367.0	45.0

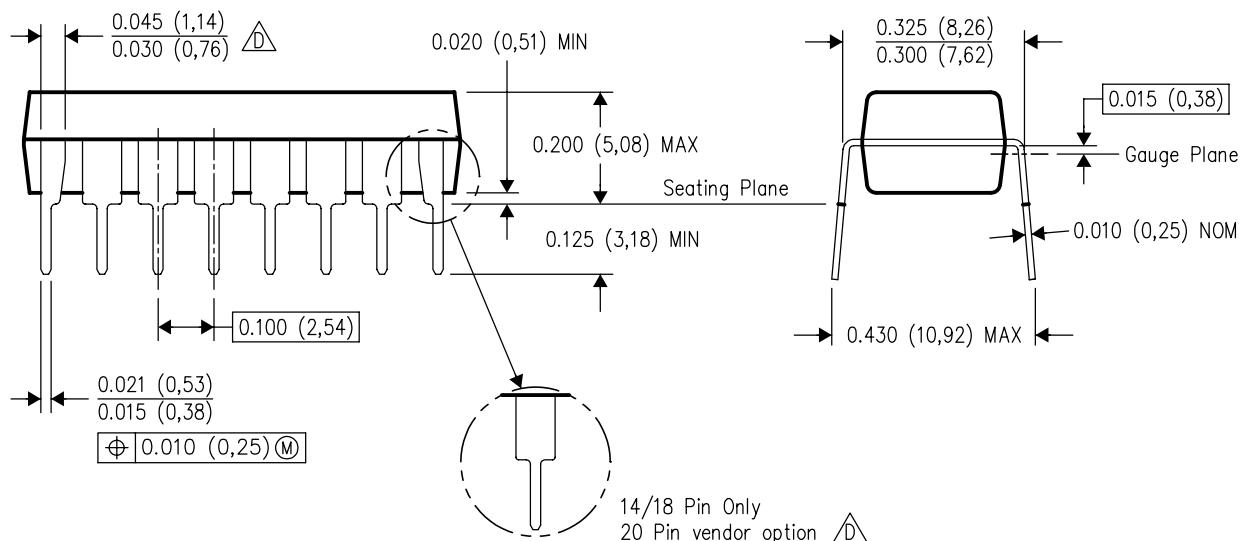
N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A MAX	0.775 (19.69)	0.775 (19.69)	0.920 (23.37)	1.060 (26.92)
A MIN	0.745 (18.92)	0.745 (18.92)	0.850 (21.59)	0.940 (23.88)
MS-001 VARIATION	AA	BB	AC	AD



4040049/E 12/2002

- NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.

Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).

The 20 pin end lead shoulder width is a vendor option, either half or full width.

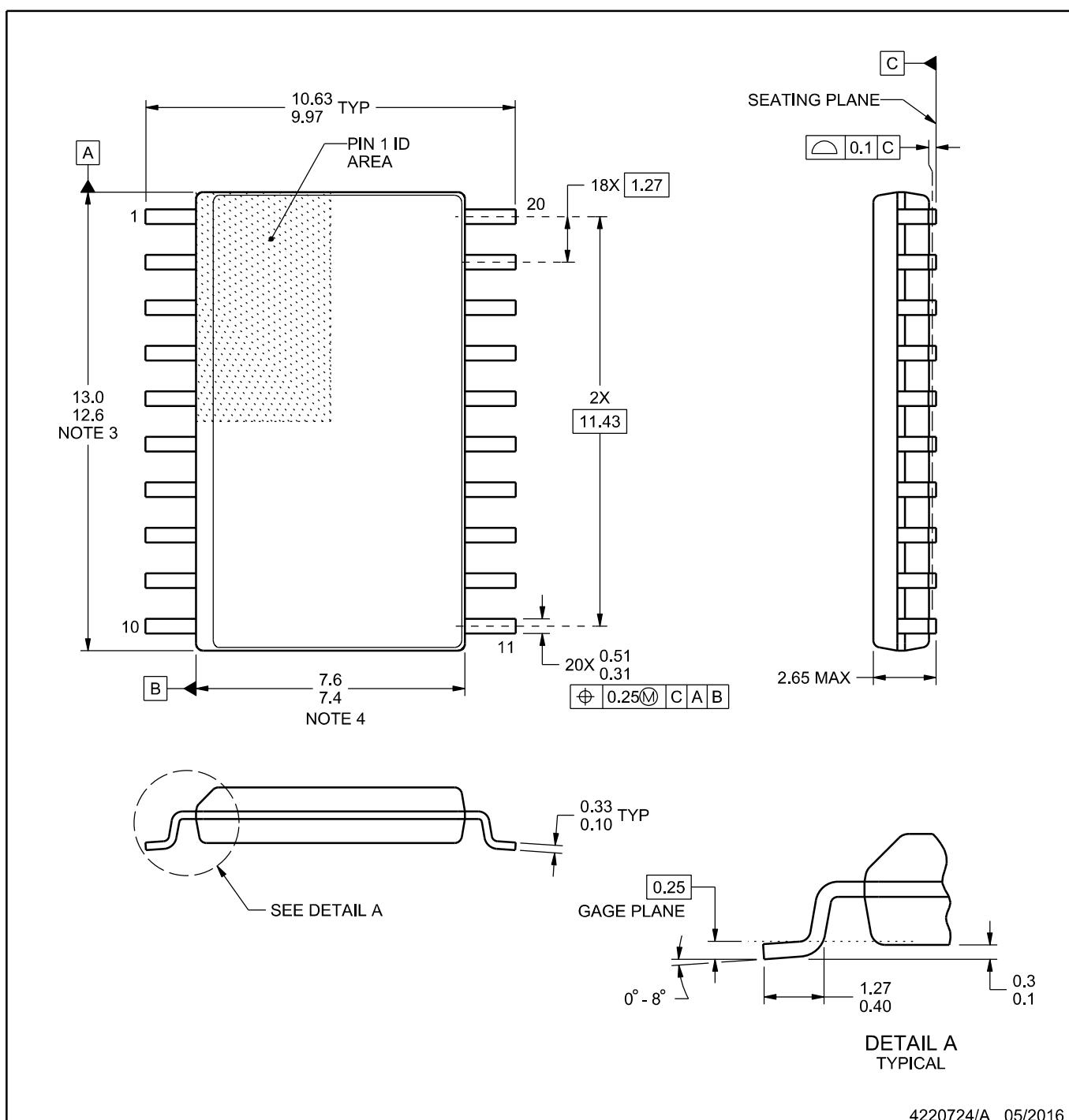
PACKAGE OUTLINE

DW0020A



SOIC - 2.65 mm max height

SOIC



NOTES:

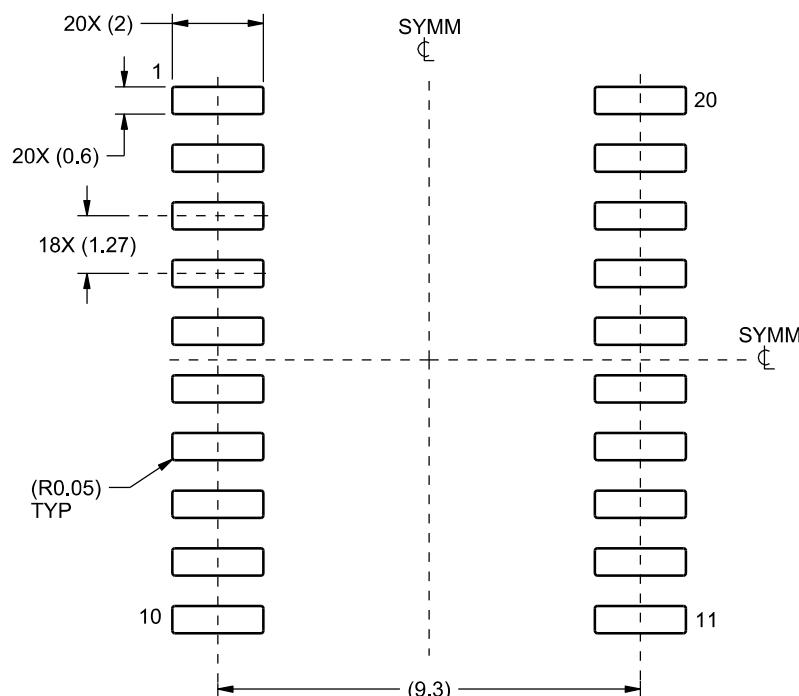
- All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- This drawing is subject to change without notice.
- This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
- This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
- Reference JEDEC registration MS-013.

EXAMPLE BOARD LAYOUT

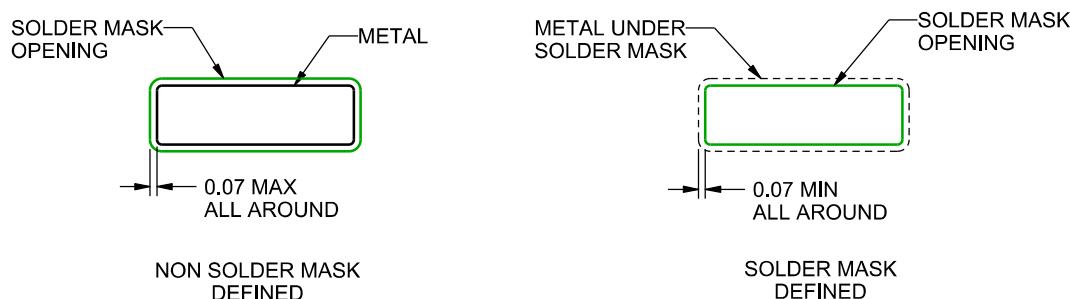
DW0020A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE
SCALE:6X



SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

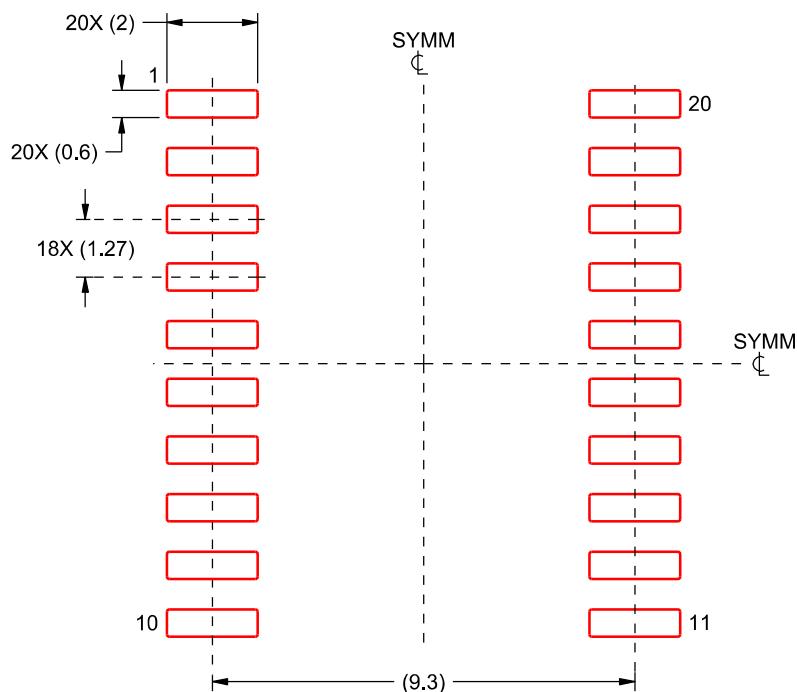
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DW0020A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

4220724/A 05/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale (www.ti.com/legal/termsofsale.html) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2020, Texas Instruments Incorporated